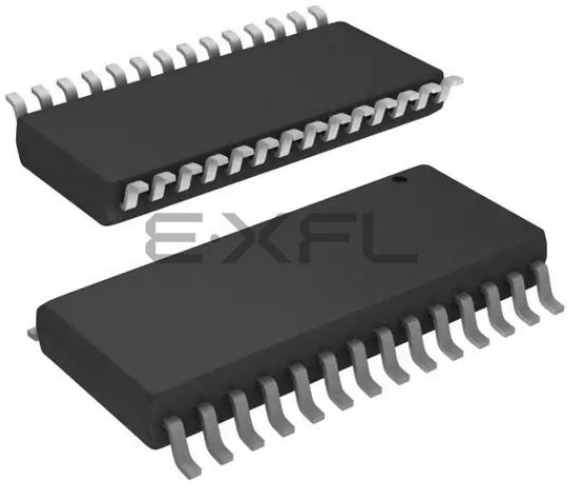

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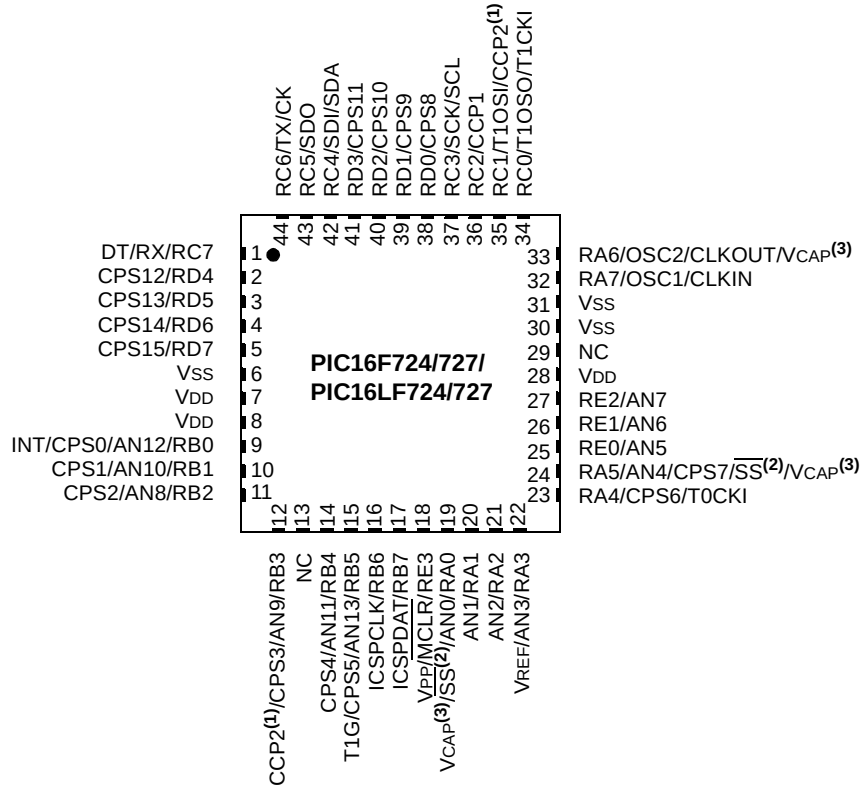
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f722-e-so

Pin Diagrams – 44-PIN QFN (PIC16F724/727/PIC16LF724/727)



Note 1: CCP2 pin location may be selected as RB3 or RC1.
2: $\overline{SS}$ pin location may be selected as RA5 or RA0.
3: PIC16F724/727 devices only.

TABLE 2-1: PIC16(L)F722/3/4/6/7 SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Page
Bank 1											
80h(2)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	29,37
81h	OPTION_REG	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	26,37
82h(2)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	28,37
83h(2)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	25,37
84h(2)	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	29,37
85h	TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1111 1111	51,37
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	60,37
87h	TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	70,37
88h(3)	TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	1111 1111	78,37
89h	TRISE	—	—	—	—	TRISE3(6)	TRISE2(3)	TRISE1(3)	TRISE0(3)	---- 1111	81,37
8Ah(1, 2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	28,37
8Bh(2)	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	44,37
8Ch	PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	45,37
8Dh	PIE2	—	—	—	—	—	—	—	CCP2IE	---- ---0	46,37
8Eh	PCON	—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$	---- --qq	27,38
8Fh	T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{DONE}$	T1GVAL	T1GSS1	T1GSS0	0000 0x00	118,38
90h	OSCCON	—	—	IRCF1	IRCF0	ICSL	ICSS	—	—	--10 qq--	87,38
91h	OSCTUNE	—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0	--00 0000	88,38
92h	PR2	Timer2 Period Register								1111 1111	120,38
93h	SSPADD(5)	Synchronous Serial Port (I^2C mode) Address Register								0000 0000	169,38
93h	SSPMSK(4)	Synchronous Serial Port (I^2C mode) Address Mask Register								1111 1111	180,38
94h	SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	179,38
95h	WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	1111 1111	61,38
96h	IOCB	IOCB7	IOCB6	IOCB5	IOCB4	IOCB3	IOCB2	IOCB1	IOCB0	0000 0000	61,38
97h	—	Unimplemented								—	—
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	147,38
99h	SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	149,38
9Ah	—	Unimplemented								—	—
9Bh	—	Unimplemented								—	—
9Ch	APFCON	—	—	—	—	—	—	SSSEL	CCP2SEL	---- --00	50,38
9Dh	FVRCON	FVRRDY	FVREN	—	—	—	—	ADFVR1	ADFVR0	q0-- --00	104,38
9Eh	—	Unimplemented								—	—
9Fh	ADCON1	—	ADCS2	ADCS1	ADCS0	—	—	ADREF1	ADREF0	0000 --00	100,38

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8>, whose contents are transferred to the upper byte of the program counter.

2: These registers can be addressed from any bank.

3: These registers/bits are not implemented on PIC16F722/723/726/PIC16LF722/723/726 devices, read as '0'.

4: Accessible only when SSPM<3:0> = 1001.

5: Accessible only when SSPM<3:0> ≠ 1001.

6: This bit is always '1' as RE3 is input-only.

4.3 Interrupts During Sleep

Some interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate Interrupt Enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to the **Section 19.0 "Power-Down Mode (Sleep)"** for more details.

4.4 INT Pin

The external interrupt, INT pin, causes an asynchronous, edge-triggered interrupt. The INTEDG bit of the OPTION register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the INTCON register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector. This interrupt is disabled by clearing the INTE bit of the INTCON register.

4.5 Context Saving

When an interrupt occurs, only the return PC value is saved to the stack. If the ISR modifies or uses an instruction that modifies key registers, their values must be saved at the beginning of the ISR and restored when the ISR completes. This prevents instructions following the ISR from using invalid data. Examples of key registers include the W, STATUS, FSR and PCLATH registers.

Note:	The microcontroller does not normally require saving the PCLATH register. However, if computed GOTO's are used, the PCLATH register must be saved at the beginning of the ISR and restored when the ISR is complete to ensure correct program flow.

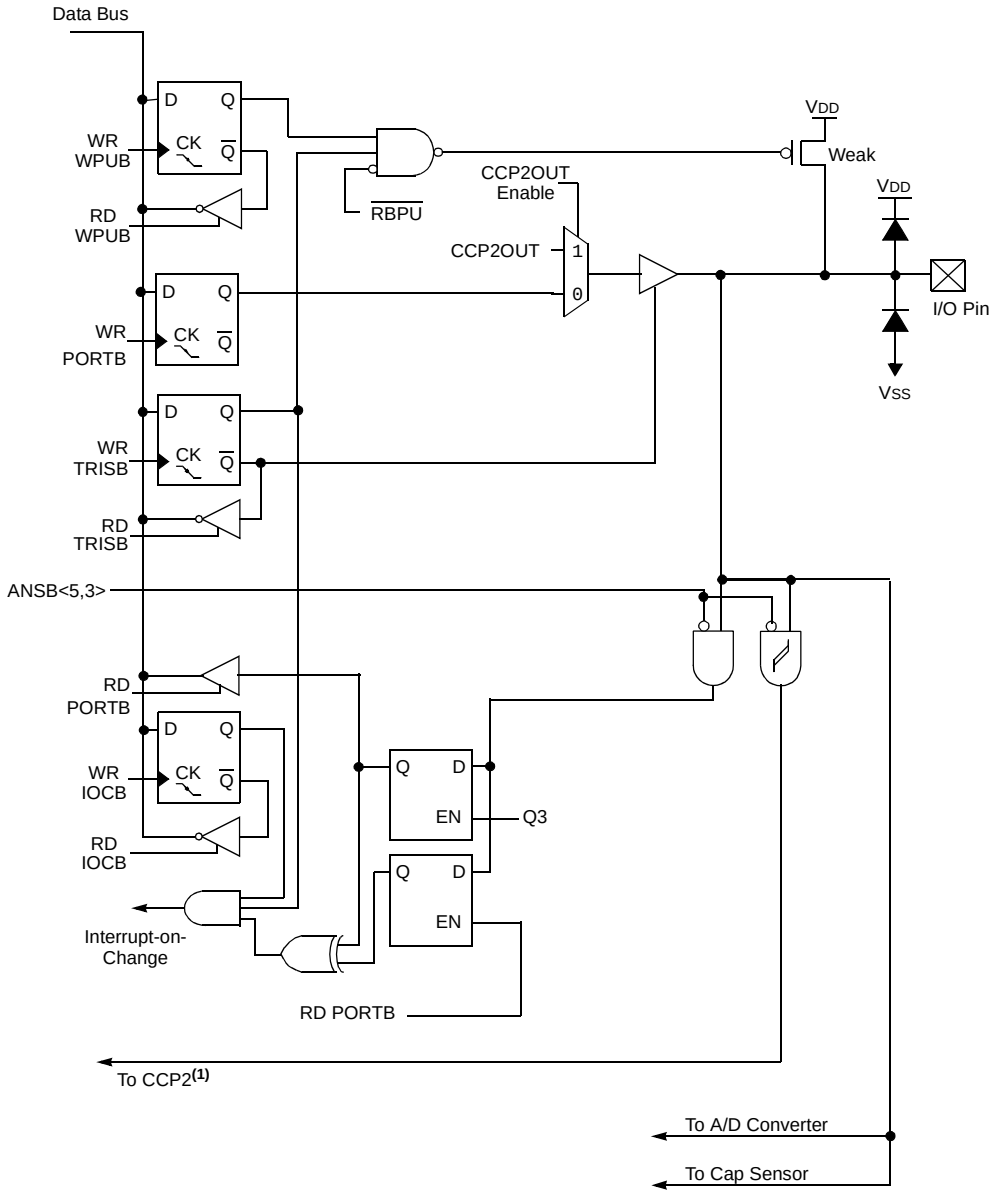
The code shown in Example 4-1 can be used to do the following.

- Save the W register
- Save the STATUS register
- Save the PCLATH register
- Execute the ISR program
- Restore the PCLATH register
- Restore the STATUS register
- Restore the W register

Since most instructions modify the W register, it must be saved immediately upon entering the ISR. The SWAPF instruction is used when saving and restoring the W and STATUS registers because it will not affect any bits in the STATUS register. It is useful to place W_TEMP in shared memory because the ISR cannot predict which bank will be selected when the interrupt occurs.

The processor will branch to the interrupt vector by loading the PC with 0004h. The PCLATH register will remain unchanged. This requires the ISR to ensure that the PCLATH register is set properly before using an instruction that causes PCLATH to be loaded into the PC. See **Section 2.3 "PCL and PCLATH"** for details on PC operation.

FIGURE 6-9: BLOCK DIAGRAM OF RB3



Note 1: CCP2 input is controlled by CCP2SEL in the APFCON register.

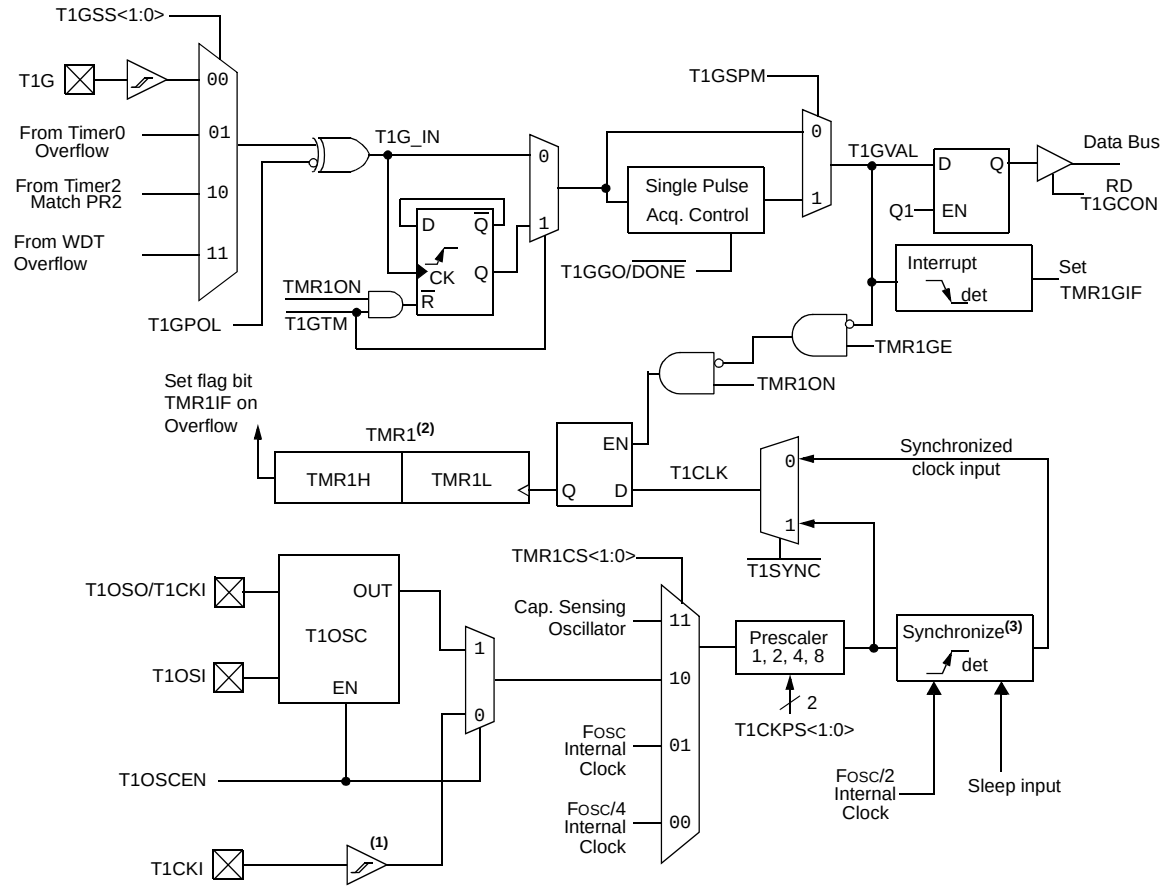
12.0 TIMER1 MODULE WITH GATE CONTROL

The Timer1 module is a 16-bit timer/counter with the following features:

- 16-bit timer/counter register pair (TMR1H:TMR1L)
- Programmable internal or external clock source
- 3-bit prescaler
- Dedicated LP oscillator circuit
- Synchronous or asynchronous operation
- Multiple Timer1 gate (count enable) sources
- Interrupt on overflow
- Wake-up on overflow (external clock, Asynchronous mode only)
- Time base for the Capture/Compare function
- Special Event Trigger (with CCP)
- Selectable Gate Source Polarity
- Gate Toggle mode
- Gate Single-pulse mode
- Gate Value Status
- Gate Event Interrupt

Figure 12-1 is a block diagram of the Timer1 module.

FIGURE 12-1: TIMER1 BLOCK DIAGRAM



Note 1: ST Buffer is high speed type when using T1CKI.
2: Timer1 register increments on rising edge.
3: Synchronize does not operate while in Sleep.

14.5 Software Control

The software portion of the capacitive sensing module is required to determine the change in frequency of the capacitive sensing oscillator. This is accomplished by the following:

- Setting a fixed time base to acquire counts on Timer0 or Timer1
- Establishing the nominal frequency for the capacitive sensing oscillator
- Establishing the reduced frequency for the capacitive sensing oscillator due to an additional capacitive load
- Set the frequency threshold

14.5.1 NOMINAL FREQUENCY (NO CAPACITIVE LOAD)

To determine the nominal frequency of the capacitive sensing oscillator:

- Remove any extra capacitive load on the selected CPSx pin
- At the start of the fixed time base, clear the timer resource
- At the end of the fixed time base save the value in the timer resource

The value of the timer resource is the number of oscillations of the capacitive sensing oscillator for the given time base. The frequency of the capacitive sensing oscillator is equal to the number of counts on in the timer divided by the period of the fixed time base.

14.5.2 REDUCED FREQUENCY (ADDITIONAL CAPACITIVE LOAD)

The extra capacitive load will cause the frequency of the capacitive sensing oscillator to decrease. To determine the reduced frequency of the capacitive sensing oscillator:

- Add a typical capacitive load on the selected CPSx pin
- Use the same fixed-time base as the nominal frequency measurement
- At the start of the fixed-time base, clear the timer resource
- At the end of the fixed-time base save the value in the timer resource

The value of the timer resource is the number of oscillations of the capacitive sensing oscillator with an additional capacitive load. The frequency of the capacitive sensing oscillator is equal to the number of counts on in the timer divided by the period of the fixed time base. This frequency should be less than the value obtained during the nominal frequency measurement.

14.5.3 FREQUENCY THRESHOLD

The frequency threshold should be placed midway between the value of nominal frequency and the reduced frequency of the capacitive sensing oscillator. Refer to Application Note AN1103, *Software Handling for Capacitive Sensing* (DS01103) for more detailed information the software required for capacitive sensing module.

Note: For more information on general Capacitive Sensing refer to Application Notes:

- AN1101, *Introduction to Capacitive Sensing* (DS01101)
- *AN1102, Layout and Physical Design Guidelines for Capacitive Sensing* (DS01102).

16.1.1.4 TSR Status

The TRMT bit of the TXSTA register indicates the status of the TSR register. This is a read-only bit. The TRMT bit is set when the TSR register is empty and is cleared when a character is transferred to the TSR register from the TXREG. The TRMT bit remains clear until all bits have been shifted out of the TSR register. No interrupt logic is tied to this bit, so the user has to poll this bit to determine the TSR status.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

16.1.1.5 Transmitting 9-Bit Characters

The AUSART supports 9-bit character transmissions. When the TX9 bit of the TXSTA register is set the AUSART will shift nine bits out for each character transmitted. The TX9D bit of the TXSTA register is the ninth, and Most Significant, data bit. When transmitting 9-bit data, the TX9D data bit must be written before writing the eight Least Significant bits into the TXREG. All nine bits of data will be transferred to the TSR shift register immediately after the TXREG is written.

A special 9-bit Address mode is available for use with multiple receivers. Refer to **Section 16.1.2.7 "Address Detection"** for more information on the Address mode.

16.1.1.6 Asynchronous Transmission Set-up:

1. Initialize the SPBRG register and the BRGH bit to achieve the desired baud rate (Refer to **Section 16.2 "AUSART Baud Rate Generator (BRG)"**).
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If 9-bit transmission is desired, set the TX9 control bit. A set ninth data bit will indicate that the eight Least Significant data bits are an address when the receiver is set for address detection.
4. Enable the transmission by setting the TXEN control bit. This will cause the TXIF interrupt bit to be set.
5. If interrupts are desired, set the TXIE interrupt enable bit of the PIE1 register. An interrupt will occur immediately provided that the GIE and PEIE bits of the INTCON register are also set.
6. If 9-bit transmission is selected, the ninth bit should be loaded into the TX9D data bit.
7. Load 8-bit data into the TXREG register. This will start the transmission.

FIGURE 16-3: ASYNCHRONOUS TRANSMISSION

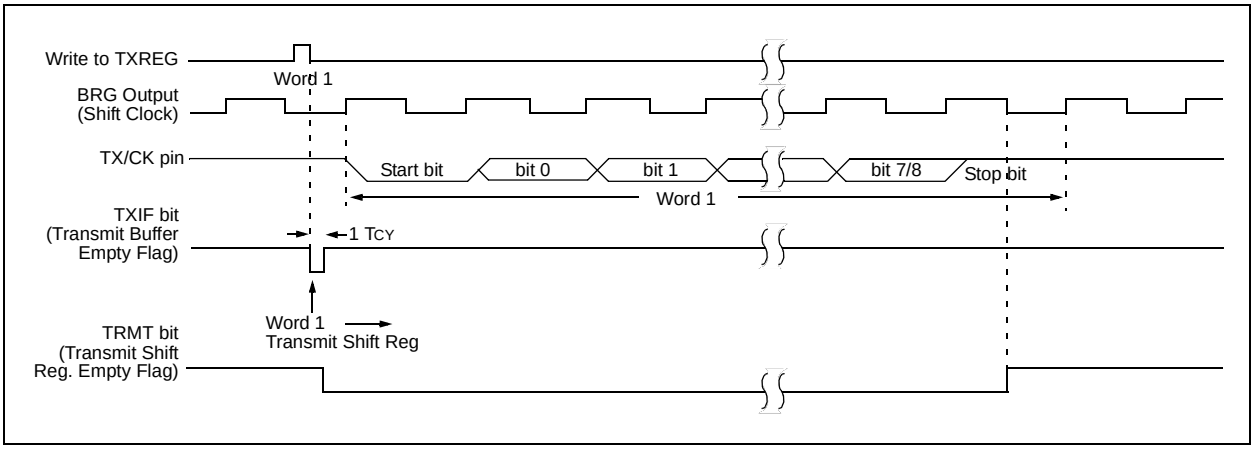
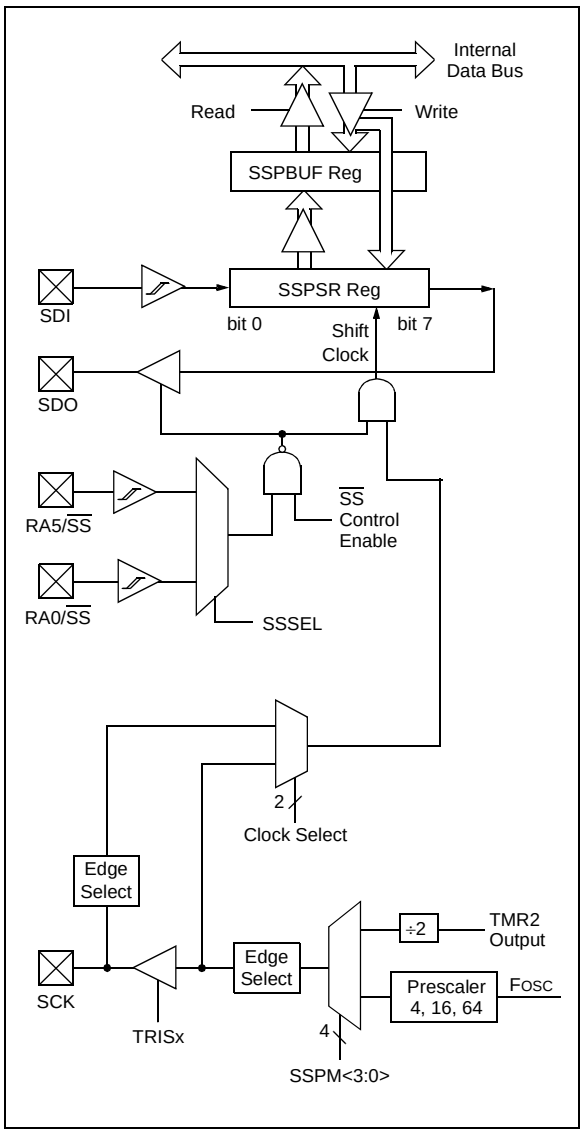


FIGURE 17-2: SPI MODE BLOCK DIAGRAM



23.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS}, PIC16F72X ..... -0.3V to +6.5V
Voltage on V_{CAP} pin with respect to V_{SS}, PIC16F72X ..... -0.3V to +4.0V
Voltage on V_{DD} with respect to V_{SS}, PIC16LF72X ..... -0.3V to +4.0V
Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +9.0V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS} pin ..... 95 mA
Maximum current into V_{DD} pin ..... 70 mA
Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports(2), -40°C ≤ T_A ≤ +85°C for industrial ..... 200 mA
Maximum current sunk by all ports(2), -40°C ≤ T_A ≤ +125°C for extended ..... 90 mA
Maximum current sourced by all ports(2), 40°C ≤ T_A ≤ +85°C for industrial ..... 140 mA
Maximum current sourced by all ports(2), -40°C ≤ T_A ≤ +125°C for extended ..... 65 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$.

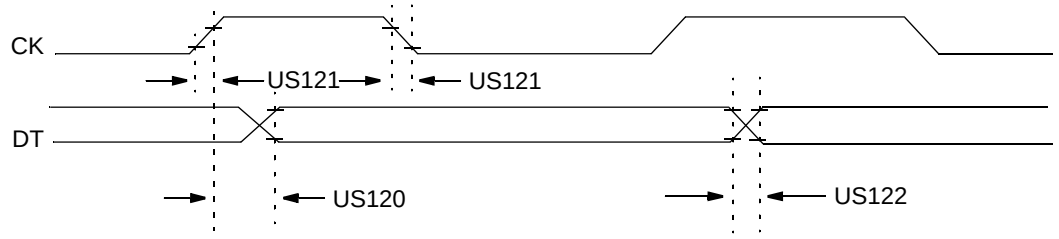
† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

23.5 Thermal Considerations

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θJA	Thermal Resistance Junction to Ambient	60	°C/W	28-pin SPDIP package
			80	°C/W	28-pin SOIC package
			90	°C/W	28-pin SSOP package
			27.5	°C/W	28-pin UQFN 4x4mm package
			27.5	°C/W	28-pin QFN 6x6mm package
			47.2	°C/W	40-pin PDIP package
			46	°C/W	44-pin TQFP package
			24.4	°C/W	44-pin QFN 8x8mm package
TH02	θJC	Thermal Resistance Junction to Case	31.4	°C/W	28-pin SPDIP package
			24	°C/W	28-pin SOIC package
			24	°C/W	28-pin SSOP package
			24	°C/W	28-pin UQFN 4x4mm package
			24	°C/W	28-pin QFN 6x6mm package
			24.7	°C/W	40-pin PDIP package
			14.5	°C/W	44-pin TQFP package
			20	°C/W	44-pin QFN 8x8mm package
TH03	TJMAX	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = PINTERNAL + PI/O
TH05	PINTERNAL	Internal Power Dissipation	—	W	PINTERNAL = IDD x VDD(1)
TH06	PI/O	I/O Power Dissipation	—	W	PI/O = Σ (IOL * VOL) + Σ (IOH * (VDD - VOH))
TH07	PDER	Derated Power	—	W	PDER = PDMAX (TJ - TA)/θJA(2)

Note 1: IDD is current to run the chip alone without driving any load on the output pins.
2: TA = Ambient Temperature
3: TJ = Junction Temperature

FIGURE 23-14: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

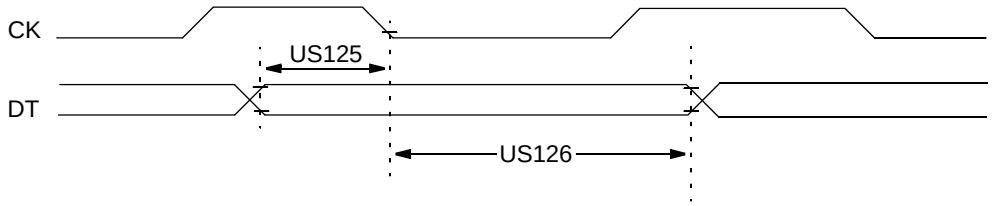


Note: Refer to Figure 23-2 for load conditions.

TABLE 23-9: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param. No.	**Symbol**	**Characteristic**		**Min.**	**Max.**	**Units**	**Conditions**
US120	TCKH2DTV	SYNC XMIT (Master and Slave) Clock high to data-out valid	3.0-5.5V	—	80	ns	
			1.8-5.5V	—	100	ns	
US121	TCKRF	Clock out rise time and fall time (Master mode)	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	
US122	TDTRF	Data-out rise time and fall time	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	

FIGURE 23-15: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 23-2 for load conditions.

TABLE 23-10: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
US125	TDTV2CKL	SYNC RCV (Master and Slave) Data-hold before CK ↓ (DT hold time)	10	—	ns	
US126	TCKL2DTL	Data-hold after CK ↓ (DT hold time)	15	—	ns	

FIGURE 23-16: SPI MASTER MODE TIMING (CKE = 0, SMP = 0)

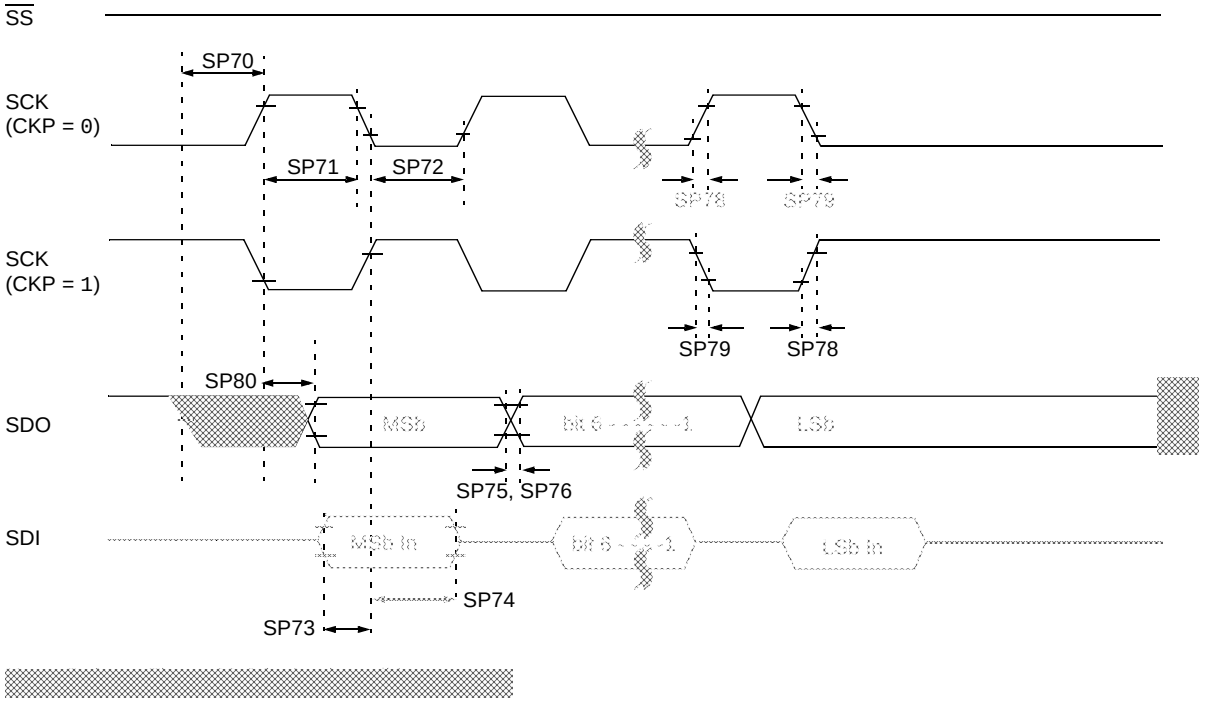
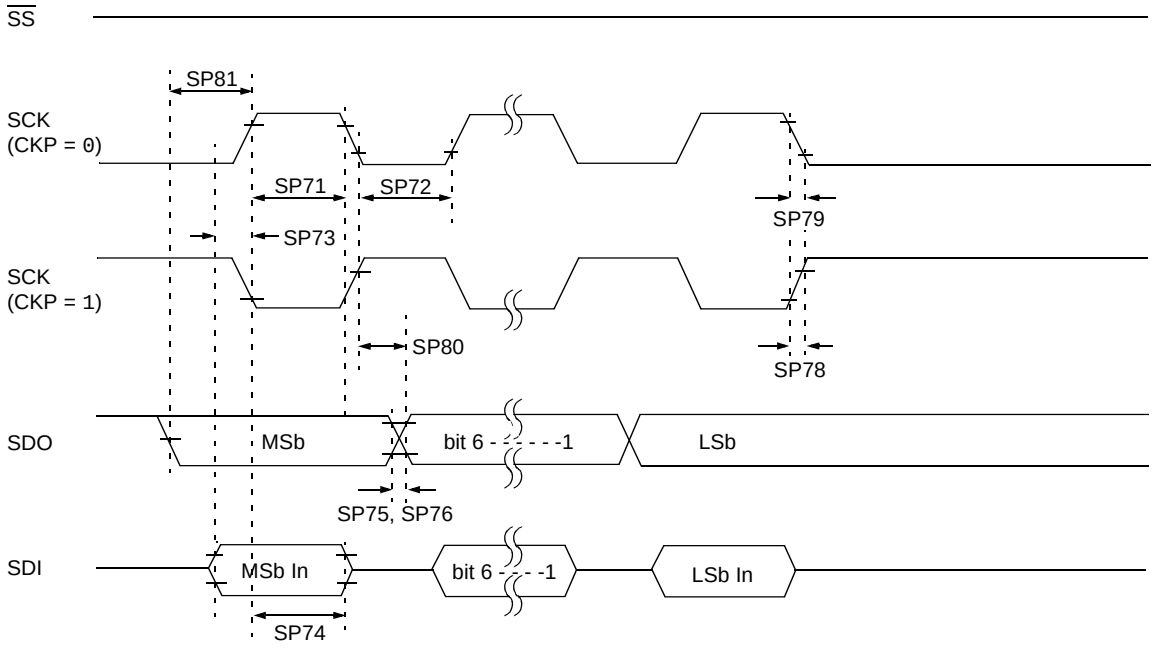


FIGURE 23-17: SPI MASTER MODE TIMING (CKE = 1, SMP = 1)



Note: Refer to Figure 23-2 for load conditions.

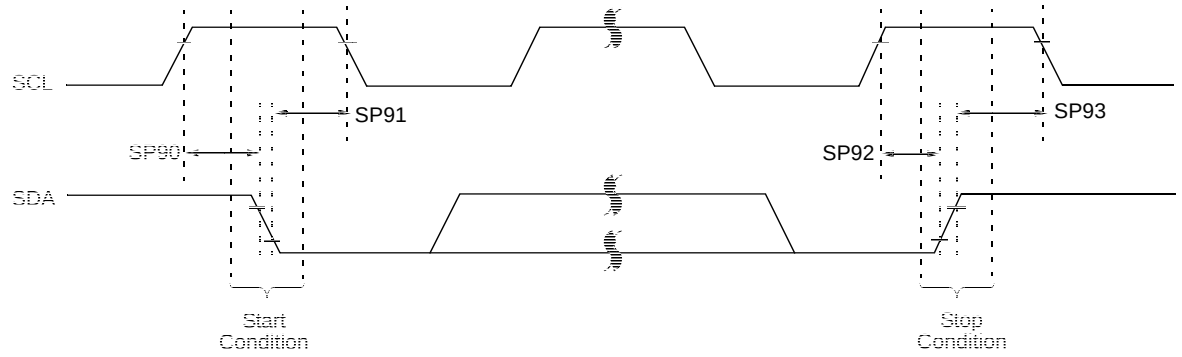
TABLE 23-11: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
SP70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK↓ or SCK↑ input		Tcy	—	—	ns	
SP71*	TscH	SCK input high time (Slave mode)		Tcy + 20	—	—	ns	
SP72*	TscL	SCK input low time (Slave mode)		Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
SP75*	TdoR	SDO data output rise time	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP76*	TdoF	SDO data output fall time		—	10	25	ns	
SP77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output high-impedance		10	—	50	ns	
SP78*	TscR	SCK output rise time (Master mode)	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	3.0-5.5V	—	—	50	ns	
			1.8-5.5V	—	—	145	ns	
SP81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	
SP82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge		—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge		1.5Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 23-20: I^2C BUS START/STOP BITS TIMING



Note: Refer to Figure 23-2 for load conditions.

24.0 DC AND AC CHARACTERISTICS GRAPHS AND CHARTS

FIGURE 24-1: PIC16F722/3/4/6/7 MAXIMUM IDD vs. FOSC OVER VDD, EC MODE, VCAP = 0.1 µF

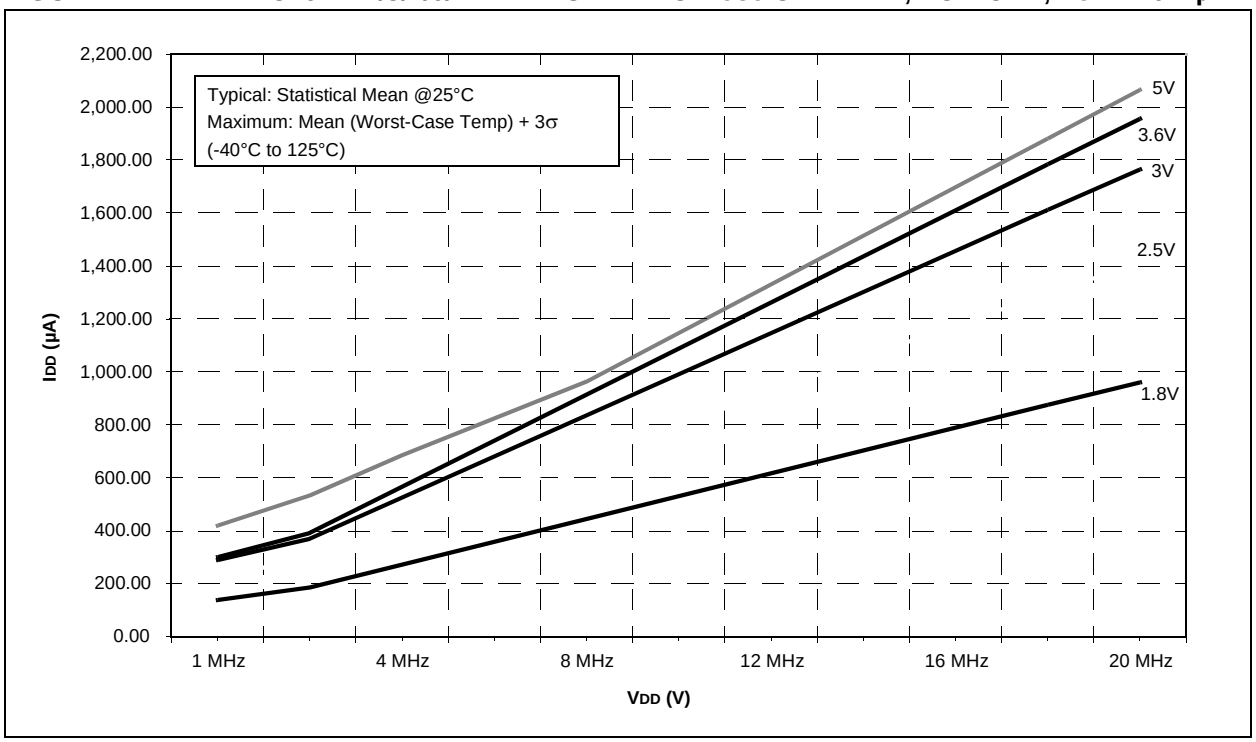


FIGURE 24-2: PIC16LF722/3/4/6/7 MAXIMUM IDD vs. FOSC OVER VDD, EC MODE

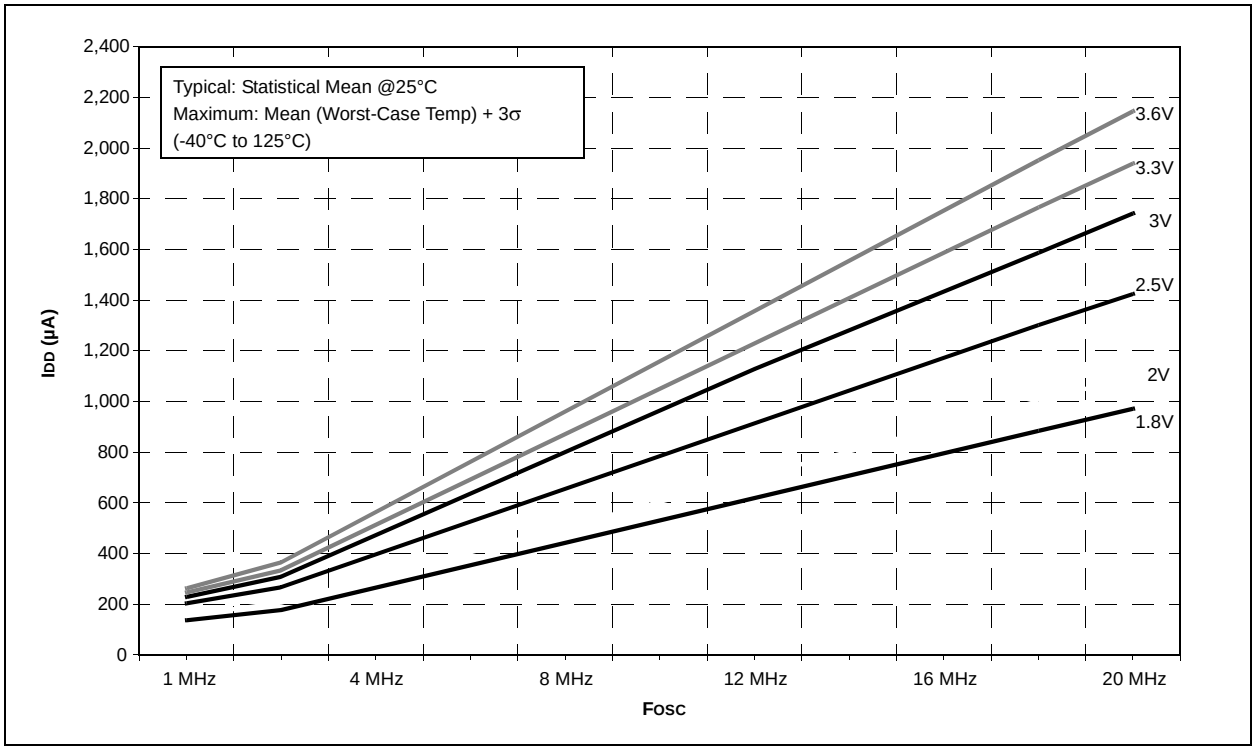


FIGURE 24-3: PIC16F722/3/4/6/7 TYPICAL IDD vs. FOSC OVER VDD, EC MODE, VCAP = 0.1 µF

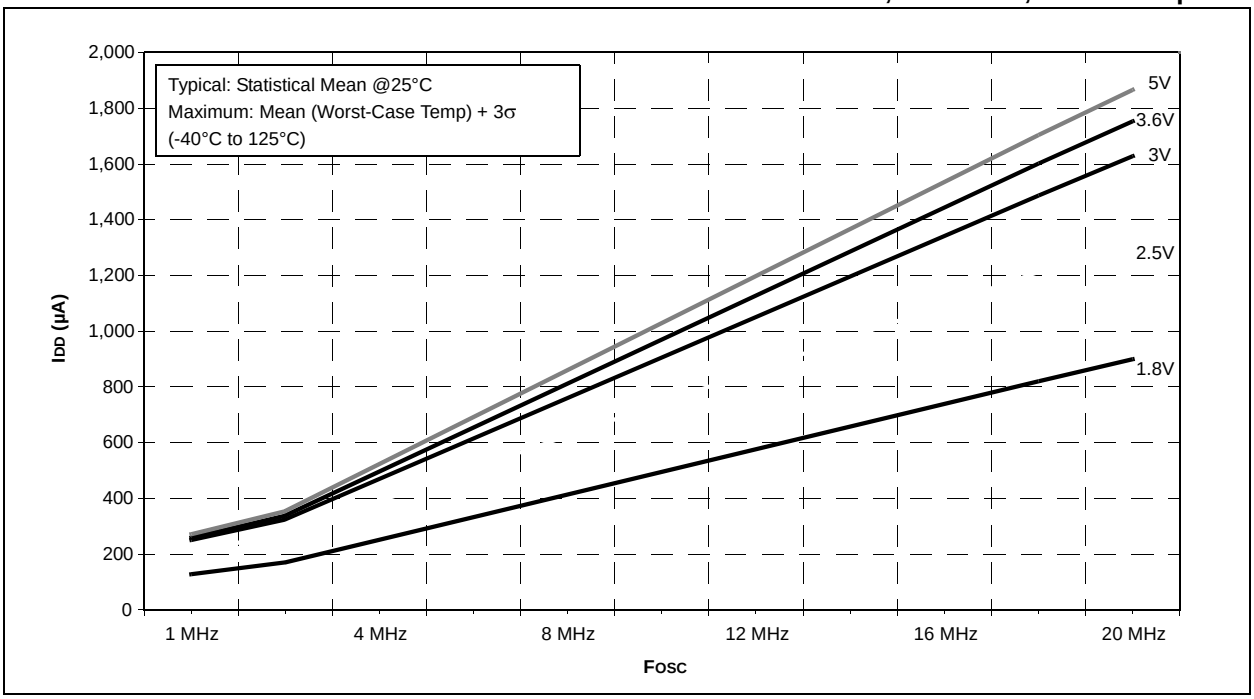


FIGURE 24-4: PIC16LF722/3/4/6/7 TYPICAL IDD vs. FOSC OVER VDD, EC MODE

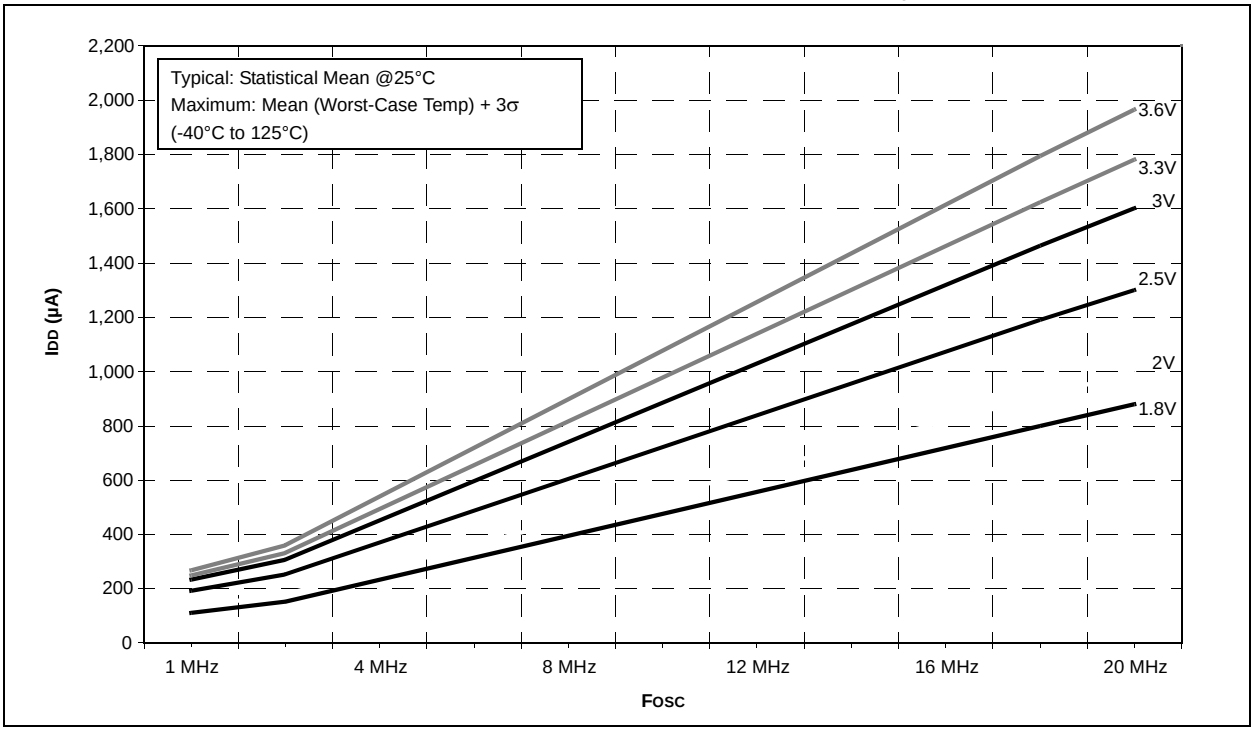


FIGURE 24-63: PIC16F722/3/4/6/7 CAP SENSE OUTPUT CURRENT, POWER MODE = MEDIUM

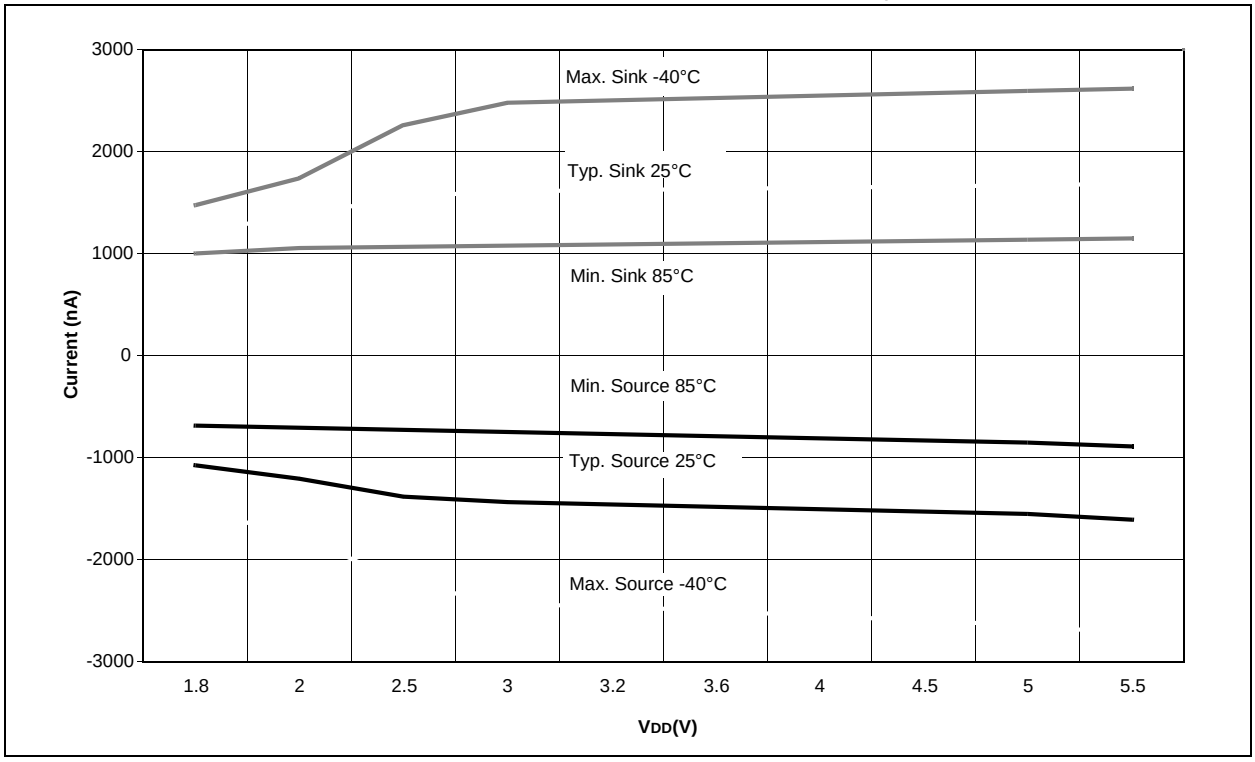


FIGURE 24-64: PIC16F722/3/4/6/7 CAP SENSE OUTPUT CURRENT, POWER MODE = LOW

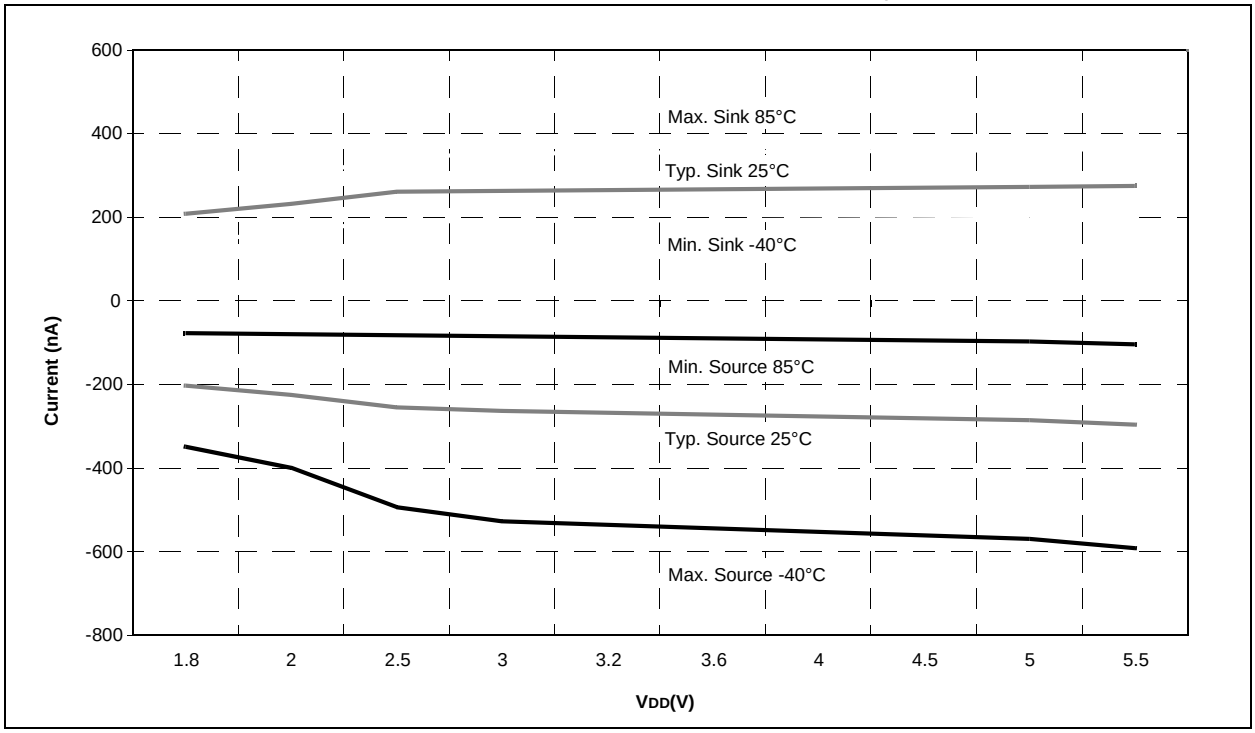


FIGURE 24-65: PIC16F722/3/4/6/7 CAP SENSOR HYSTERESIS, POWER MODE = HIGH

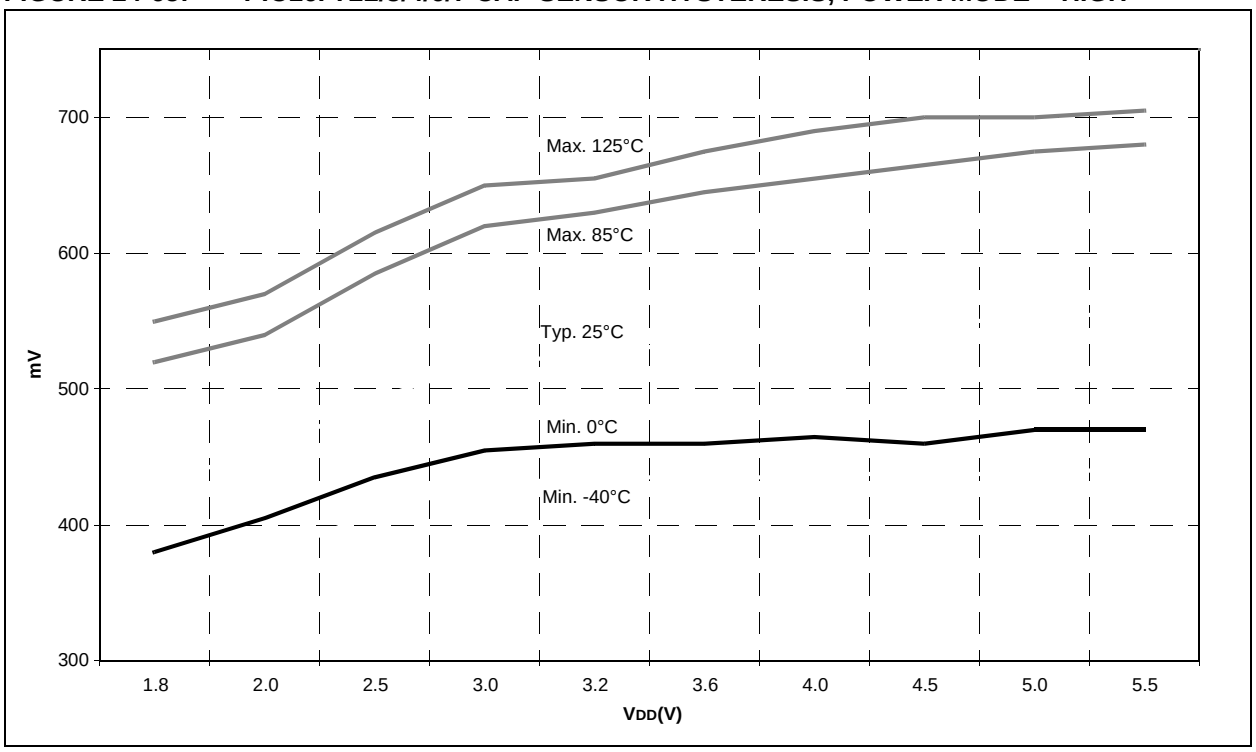
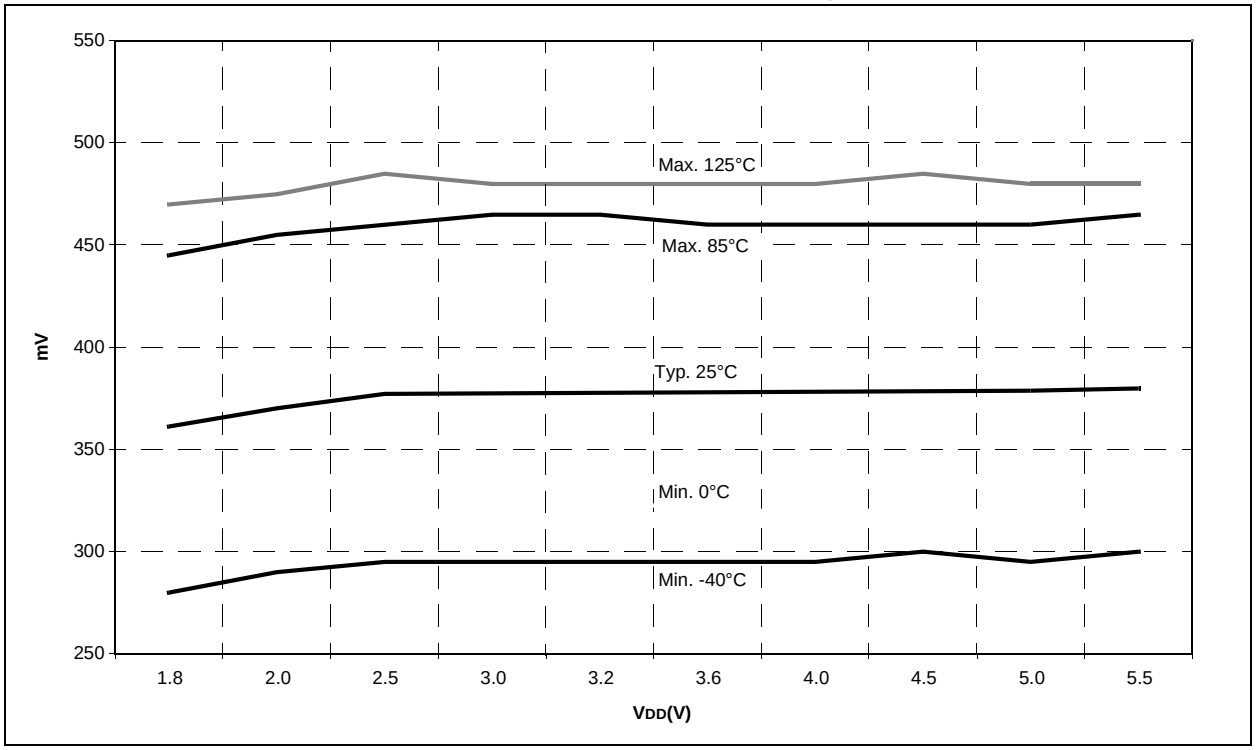
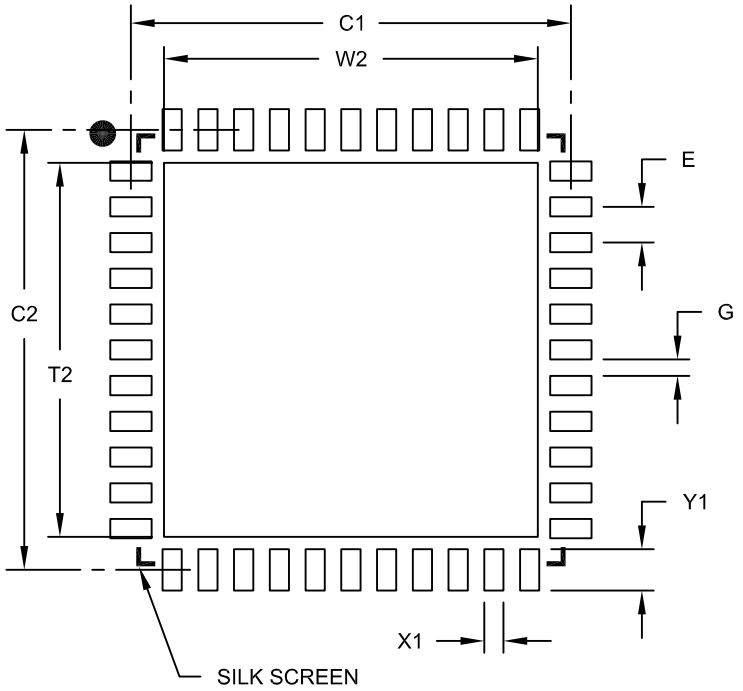


FIGURE 24-66: PIC16F722/3/4/6/7 CAP SENSOR HYSTERESIS, POWER MODE = MEDIUM



44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

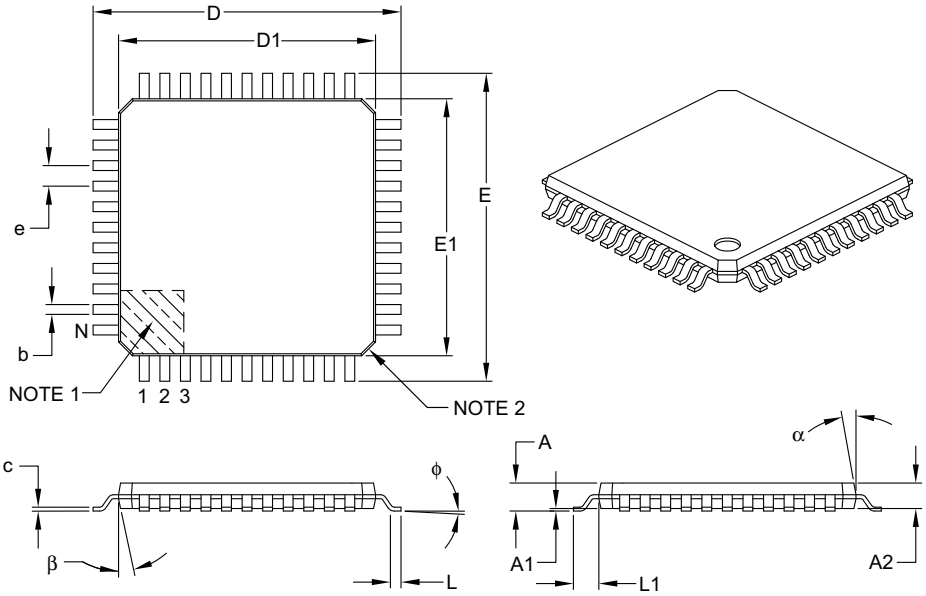
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (12/2007)

Original release.

Revision B (08/2008)

Electrical Specification updates; Package Drawings; miscellaneous updates.

Revision C (04/2009)

Revised data sheet title; Revised Low-Power Features section; Revised Section 6.2.2.4 RA3/AN3/VREF; Revised Figure 16-8 Synchronous Reception.

Revision D (07/2009)

Removed the Preliminary Label; Updated the “Electrical Characteristics” section; Added charts in the “Char. Data” section; Deleted “Based 8-Bit CMOS” from title; Updated the “Special Microcontroller Features” section and the “Peripheral Features” section; Changed the title of the “Low Power Features” section into “Extreme Low-Power Management PIC16LF72X with nanoWatt XLP” and updated this section; Inserted new section – “Analog Features” (page 1); Changed the title of the “Peripheral Features” section into “Peripheral Highlights” and updated the section.

Revision E (10/2009)

Added paragraph to section 5.0 (LDO Voltage Regulator); Updated the Electrical Specifications section (Added another absolute Maximum Rating; Updated section 23.1 and Table 23-4); Updated the Pin Diagrams with the UQFN package; Updated Table 1, adding UQFN; Updated section 23.5 (Thermal Considerations); Updated the Packaging Information section adding the UQFN Package; Updated the Product Identification System section.

Revision F (12/2015)

Updated Table 2; Updated 23.1, 23.3 and 9.2.4 Sections; Updated Figure 23-9; Other minor corrections.

APPENDIX B: MIGRATING FROM OTHER PIC® DEVICES

This discusses some of the issues in migrating from other PIC® devices to the PIC16F72X family of devices.

B.1 PIC16F77 to PIC16F72X

TABLE B-1: FEATURE COMPARISON

Feature	PIC16F77	PIC16F727
Max. Operating Speed	20 MHz	20 MHz
Max. Program Memory (Words)	8K	8K
Max. SRAM (Bytes)	368	368
A/D Resolution	8-bit	8-bit
Timers (8/16-bit)	2/1	2/1
Oscillator Modes	4	8
Brown-out Reset	Y	Y
Internal Pull-ups	RB<7:0>	RB<7:0>
Interrupt-on-change	RB<7:4>	RB<7:0>
Comparator	0	0
USART	Y	Y
Extended WDT	N	N
Software Control Option of WDT/BOR	N	N
INTOSC Frequencies	None	500 kHz - 16 MHz
Clock Switching	N	N